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(54) **Title:** METHOD AND APPARATUS TO PREWET WAFER SURFACE FOR METALLIZATION FROM ELECTROLYTE SOLUTION

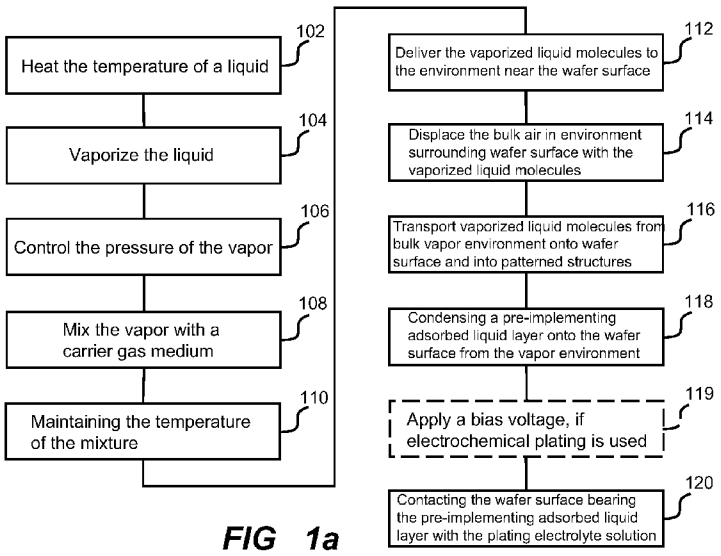


FIG 1a

(57) **Abstract:** A method and an apparatus to prewet wafer surface for metallization are provided. The wetting between electrolyte solution and the wafer surface is improved when they are put into contact by pre-implementing an adsorbed liquid layer on the entire front surface of the wafer just prior to the plating process. The pre-implementing adsorbed liquid layer is realized by transporting vaporized liquid molecules from vapor phase at elevated temperature (relative to wafer) and condensing them onto the wafer surface.

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